

AMENDMENTS TO THE CLAIMS

The claims below replace all prior claims herein Claims 1 to 25 are canceled.

Cancel 1-25 (canceled).

Claims 26 (new): An electronic component comprising:

a semiconductor chip having a first surface and a second surface, said first surface comprising multiple pads; and

an encapsulating structure comprising a non-black material and over said second surface.

Claim 27 (new): The electronic component of claim 26 comprising multiple bumps connected to said multiple pads.

Claim 28 (new): The electronic component of claim 26 further comprising a substrate, wherein said semiconductor chip is connected to said substrate in a flip-chip fashion.

Claim 29 (new): The electronic component of claim 26, wherein said second surface comprises a mark under said encapsulating structure.

Claim 30 (new): The electronic component of claim 29, wherein said mark comprises a number.

Claim 31 (new): The electronic component of claim 29, wherein said mark comprises a bar code.

Claim 32 (new): The electronic component of claim 29, wherein said mark comprises an identity for a product.

Claim 33 (new): The electronic component of claim 29, wherein said mark comprises an identity for a manufacturer.

Claim 34 (new): The electronic component of claim 29, wherein said mark is visible through said encapsulating structure.

Claim 35 (new): The electronic package of claim 33, wherein said laser readable mark comprises an identity for a product.

Claim 36 (new): The electronic package of claim 33, wherein said laser readable mark comprises an identity for a manufacturer.

Claim 37 (new): The electronic package of claim 33 comprising a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said laser readable mark, said protecting structure being over said laser readable mark, wherein said mark is visible through said protecting structure.

Claim 38 (new): A semiconductor chip having a surface with a laser readable mark.

Claim 39 (new): The semiconductor chip of claim 38, wherein said laser readable mark comprises bar code.

Claim 40 (new): The semiconductor chip of claim 38, wherein said laser readable mark comprises an identity for a product.

Claim 41 (new): The semiconductor chip of claim 38, wherein said laser readable mark comprises an identity for a manufacturer.

Claim 42 (new): The semiconductor chip of claim 38, wherein said surface further comprises multiple pads.

Claim 43 (new): The semiconductor chip of claim 38, wherein said semiconductor chip has another surface with multiple pads.

Claim 44 (new): An electronic package comprising:

    a semiconductor chip having a first surface with multiple pads and a second surface with a mark; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

Claim 45 (new): The electronic package of claim 44, wherein said mark comprises bar code.

Claim 46 (new): The electronic package of claim 44, wherein said mark comprises a number.

Claim 47 (new): The electronic package of claim 44, wherein said mark comprises an identity for a product.

Claim 48 (new): The electronic package of claim 44, wherein said mark comprises an identity for a manufacturer.

Claim 49 (new): The electronic package of claim 44, wherein said mark is colored.

Claim 50 (new): An electronic package comprising:

a semiconductor chip having a surface with a mark comprising a number, a bar code, or an identity for a product or a manufacturer; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

Claim 51 (new): The semiconductor chip of claim 50, wherein said surface further comprises multiple pads.

Claim 52 (new): The semiconductor chip of claim 50, wherein said semiconductor chip has another surface with multiple pads.